INVITATION

It is our pleasure to announce that the 18th International Symposium on Microelectronics and Packaging jointed with the 21st International Conference on Electronic Materials and Packaging (ISMP-EMAP 2019) will be held at Hotel Aqua Palace, Busan, Korea, on November 13-15, 2019. This international conference is organized by KMEPS (the Korean Microelectronics and Packaging Society), and will address comprehensive coverage of recent advances in electronic packaging process and materials. Three days of technical sessions for oral and poster presentations. This will provide an excellent opportunity for researchers and engineers of academic institutes and industries to discuss recent advances and new technology directions. We cordially invite you to submit abstracts for the conference, and look forward to welcoming you in Korea.

SYMPOSIUM TOPICS

ISMP-EMAP2019 will include all fundamental and applied sciences and technologies related to the fields of electronic materials, devices, and packaging. Topics may include from, but are not limited to, the following areas:

- Advanced Packaging Technologies
- Electronic Materials for Interconnects and Packaging
- Emerging Process for Interconnects and Packaging
- PCB, Solder, and Assembly Process
- Power Electronic Packaging
- Sensors, LED, and Emerging Packaging Technology
- Wearable and Printed Electronics
- MEMS/NEMS Packaging and Applications
- Reliability of Electronic Devices and Systems
- Design Tools and Modeling

*It should be noted that the program committee reserves the right to make a final decision on the session and presentation type of oral or poster regardless of author's preference.

IMPORTANT DATES

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<tr>
<td>Submission of Abstract</td>
<td>August 23, 2019</td>
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<tr>
<td>Notification of Acceptance</td>
<td>September 20, 2019</td>
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<td>Submission of Final Manuscript</td>
<td>December 31, 2019</td>
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CONFERENCE LANGUAGE

The official language of the symposium is English.

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Visit the ISMP-EMAP 2019 website (http://www.ismp-emap2019.org) for additional symposium information.

Organized by  The Korean Microelectronics and Packaging Society (KMEPS)